

LSDPAD1 LOW LEAKAGE PICO-AMP DUAL DIODE



Linear Systems replaces discontinued Siliconix LSDPAD1

The LSDPAD1 is a low leakage Monolithic Dual Pico-Amp Diode

The LSDPAD1 extremely low-leakage monolithic dual diode provides a superior alternative to conventional diode technology when reverse current (leakage) must be minimized. In addition the monolithic dual construction allows excellent capacitance matching per diode. The LSDPAD1 features a leakage current of -1 pA and is well suited for use in applications such as input protection for operational amplifiers.

LSDPAD1 Benefits:

- Negligible Circuit Leakage Contribution
- Circuit "Transparent" Except to Shunt High-Frequency Spikes
- Simplicity of Operation

LSDPAD1 Applications:

- Op Amp Input Protection
- Multiplexer Overvoltage Protection

FEATURES						
DIRECT REPLACEMENT FOR SILICONIX LSDPAD1						
HIGH ON ISOLATION	20fA					
EXCELLENT CAPACITANCE MATCHING	$\Delta C_R \le 0.2 pF$					
ULTRALOW LEAKAGE	≤ 1 pA					
REVERSE BREAKDOWN VOLTAGE	BV _R ≥ -45V					
REVERSE CAPACITANCE	C _{rss} ≤ 0.8pF					
ABSOLUTE MAXIMUM RATINGS						
@ 25°C (unless otherwise noted)						
Maximum Temperatures						
Storage Temperature	-65°C to +150°C					
Operating Junction Temperature	-55°C to +135°C					
Maximum Power Dissipation						
Continuous Power Dissipation	ntinuous Power Dissipation 500mW					
MAXIMUM CURRENT						
Forward Current (Note 1)	50mA					

LSDPAD1 ELEC	TRICAL CHARACTERISTICS @ 25°C (unle	ss otherv	vise noted)	1		
SYMBOL	CHARACTERISTICS	MIN.	TYP.	MAX.	UNITS	CONDITIONS
BV_R	Reverse <mark>Br</mark> eakdown <mark>V</mark> oltage	-45			V	$I_R = -1\mu A$
V_{F}	Forward Voltage		0.8	1.5	>	I _F = 1mA
C_{rSS}	Total Reverse Capacitance		1	0.8	pF	$V_R = -5V$, $f = 1MHz$
C _{R1} -C _{R2}	Differential Capacitance (ΔC _R)		-	0.2	pF	$V_{R1} = V_{R2} = -5V, f = 1MHz$
I _R	Maximum Reverse Leakage Current			-1	рА	V _R = - 20V

Notes:

1. Absolute maximum ratings are limiting values above which LSDPAD1 serviceability may be impaired.

Available Packages:

LSDPAD1 in TO-78 LSDPAD1 available as bare die

Please contact Micross for full package and die dimensions

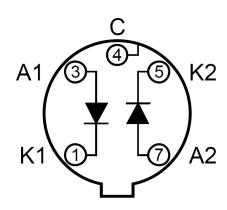


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TO-78 (Bottom View)



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